

S1155

(ANSI:FR-4) Halogen-Free

特点

- 不含卤素、锑、红磷等有毒成分。
- 燃烧时，不产生剧毒气体和残留有毒成分。
- 加工性能及其他性能与普通FR-4相同。

FEATURES

- Free of toxic constituents such as halogen, antimony, red phosphorous, etc..
- No toxic gas emission and no hazardous residue during waste combustion.
- PCB processing and other properties similar to conventional FR-4.

应用领域

电脑、仪器仪表、摄象机、电视机、电子游戏机等。

APPLICATIONS

Computer, Instrumentation, VCR, TV, electronic game machine, etc.

GENERAL PROPERTIES

Test Item	Treatment Condition	Unit	Property Data	
			SPEC	Typical Value
Tg	DSC		125	135
Flammability	C-48/23/50	-	V-0	V-0
	E-24/125			
Volume Resistivity	After moisture resistance	M -cm	10 ⁶	4.5 × 10 ⁷
	E-24/125		10 ³	4.9 × 10 ⁶
Surface Resistance	After moisture resistance	M	10 ⁴	8.6 × 10 ⁶
	E-24/125		10 ³	2.0 × 10 ⁶
Arc Resistance	D-48/50+D-0.5/23	S	60	115
Dielectric Breakdown	D-48/50+D-0.5/23	KV	40	55
Dielectric Constant (1MHz)	C-24/23/50	-	5.4	4.7
Dissipation Factor (1MHz)	C-24/23/50	-	0.035	0.010
Thermal Stress	Unetched	-	No delamination	No delamination
	Etched			
Peel Strength	1oz Cu. Foil	N/mm	1.05	1.4
			125	0.70
Flexural Strength	LW	MPa	415	590
	CW		345	485
Water Absorption	D-24/23	%	0.35	0.11
CTE z-axis	Before Tg	TMA	μ m/m	40.5
	After Tg		μ m/m	254

Specimen Thickness:1.6mm

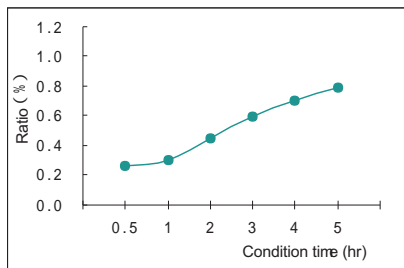
Explanations: C = Humidity conditioning;
D = Immersion conditioning in distilled water;
E = Temperature conditioning.

The figures following the letter symbols indicate with the first digit the duration of the preconditioning in hours, with the second digit the preconditioning temperature in and with the third digit the relative humidity.

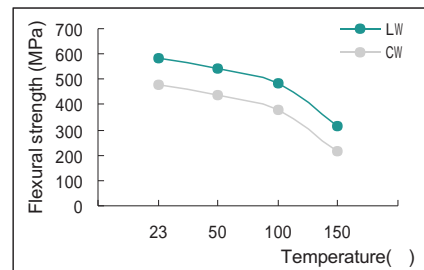
S1155

(ANSI:FR-4) Halogen-Free Copper Clad Laminate

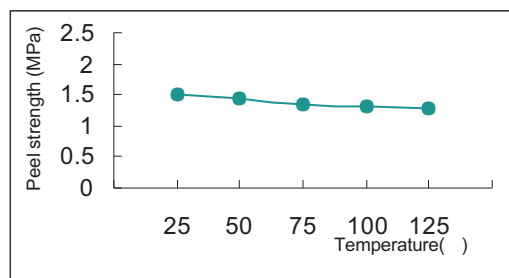
Water absorption at pressure cooker



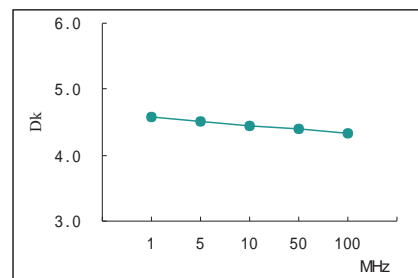
Flexural strength



Peel strength



Dielectric constant

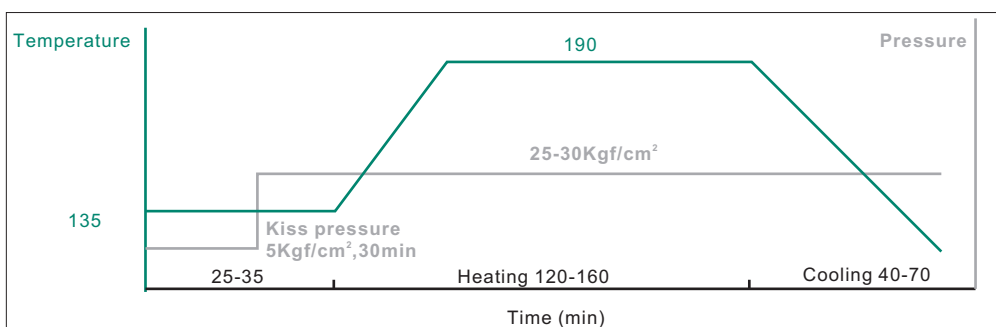


PURCHASING INFORMATION

Thickness	Copper foil	Standard Size	
0.1mm to 3.2mm	12 μ m to 105 μ m	1,020 × 1,220mm (40 × 48)	915 × 1,220mm (36 × 48)
		1,070 × 1,220mm (42 × 48)	

❖ Other sheet size and thickness could be available upon request.

RECOMMENDED PRESS CYCLES



❖ Recommended multilayer cure condition

Hold for 190 at least 60 minutes, to allow the resin to cure completely.